



SMD Comm X8G HT150C, Ceramic, 0.027 uF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	40 mg
Shelf Life	78 Weeks
MSL	1

0.027 uF

Dimensions	
Chip Size	1210
L	3.2mm +/-0.2mm
W	2.5mm +/-0.2mm
Т	1.25mm +/-0.15mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

L	3.2mm +/-0.2mm	Measurement Condition	1 kHz 1.0Vrms
W	2.5mm +/-0.2mm	Tolerance	20%
Т	1.25mm +/-0.15mm	Voltage DC	250 VDC
S	1.5mm MIN	Dielectric Withstanding Voltage	625 VDC
В	0.5mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
Packaging	T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	,, ,
Packaging Quantity	10000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
		Aging Rate	0% Loss/Decade Hour: Referee

Specifications

Capacitance

Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	37.037 GOhms	

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